



RoodMicrotec Newsletter

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Successful visit to Asia

Earlier this month, Reinhard Pusch and myself travelled to Asia, where we met with six of our business partners, both customers and suppliers.

We spoke extensively about our new strategy, which is focused on applications in three markets that are key for us: Industrial and Automotive, Hi-rel/Space and Medical.

These fields involve chips for applications in homes (smart grid and smart metering), GPS-applications in agriculture, parking

systems in cars and implants that can restore sight to practically blind people.

As we have stressed before, these are projects that have long lead-up times, but also a great deal of promise.

Our views were received very well, and have resulted in closer cooperation with a

number of our Asian partners.

RoodMicrotec is eager to expand its partnerships there, because developments in Europe remain disappointing.

We will keep you informed of further developments in our newsletter.

RoodMicrotec seminar:

Printed circuit assembly failures and their prevention

On 16 October, RoodMicrotec will organise a seminar on this theme, which will provide valuable scientific and practical insights into diagnosing and preventing failures in printed circuit assemblies.

Device processing at PCA level contains numerous risks of early failures or reduced reliability. One major factor is the manufacturing process, which comprises for instances soldering, cleaning, vanishing or encapsulating steps. Another major factor are the rules determining the layout of the device (e.g. capacitors, inductors or push-buttons) and the design of the interfaces.

The continuously increasing complexity and miniaturization of the designs requires that further consideration be given to external influences such as electrostatic discharge (ESD) or environmental factors. Further topics covered in this seminar are cooling, minimum distances between PCB tracks, quality metrics of the PCB as well as interface design for high voltage operation.

Finally, typical failure patterns and methods recognising these patterns will be presented.

The seminar is especially interesting for engineers and designers working in the fields of design, development or manufacturing of PCB or PBA. Additionally, layout designers in general and supply chain specialists will also benefit greatly from this seminar.

The general seminar language will be German. However, if a sufficient number of English-speaking participants will register, a simultaneous translation and English documents will be provided.

The deadline for registration is 26 September 2014. For more information, see www.roodmicrotec.com



Information meeting on 25 September for shareholders, bondholders and other interested parties

Recently, we have undertaken to intensify communications with our target groups. In that context, we will be organising an information meeting on 25 September (see also the 2 September press release) on the theme: **'Co-creating, collaborating and co-investing'**.

At this meeting, we will give a presentation, illustrated by actual cases, on market developments and how we have adjusted our strategy in response to them.

That strategy adjustment has been to increasingly offer a complete product of integrated services throughout the lifetime of the product - the chip. In this way, we will contribute more actively to new product development (co-creating and collaborating), which will result in recurring sales and in long-term projects that yield stabler, more predictable and less cyclic sales.

The new strategy also means co-investing in new and promising projects, which is also aimed at breaking through the ongoing lending restraint in the financial markets.

In the panel discussion following the presentation, which will be attended by several of our sales managers, there will be ample time to ask questions and exchange views.

The programme is as follows.

- 3:45pm : reception
- 4:00pm : shared presentation by Philip Nijenhuis, CEO, and Reinhard Pusch (CSO)
- 4:30pm : panel discussion with Philip Nijenhuis, Reinhard Pusch, Vic Tee (supervisory director) and sales managers
- 5:30pm : Euronext 'bell' ceremony
- 6:00pm : close and drinks

Location : Euronext, Beursplein 5, Amsterdam.

If you would like to attend the meeting, please send an email to: melden-event@roodmicrotec.com.
Registration closes on 18 September.



Introduction of Sebastian Axmann

In April, Sebastian Axmann joined RoodMicrotec's failure analysis lab. He studied electrical engineering at the University of Rostock (Germany) and ETH Zürich (Switzerland).

During his master's studies, he already worked at Empa's reliability science and technology department.

After obtaining his master's degree, he worked at RWTH Aachen University for several years. His major research focus was the novel field of carbon-based semiconductors for organic solar cells.

'For me, the field of failure analysis offers an astounding number of interesting challenges, which combine electrical engineering, physics, chemistry and material science. The broad and in-depth experience of the team on recent issues in the whole industry is a highly valuable asset to all customers. I hope to be able to strengthen the failure analysis lab with my knowledge and experience in the field of semiconductor research as well as automated data analysis and acquisition.'

In the medium term, Sebastian's main focus will be on analysis in the field of the automotive and high-reliability industry. In the longer term, he will also work on the growing medical devices market.



Agenda 2014



16 October 2014

Seminar
RoodMicrotec

Stuttgart, Germany



22 - 23 October 2014

Electronics
Design Show

Coventry, Great Britain De Vere Hotel
at the Ricoh Arena

RoodMicrotec will perform a seminar of Failure and Technology Analysis, Qualification & Reliability at the Electronics Design Show



28 - 30 October 2014

Airtec

Frankfurt, Germany Hall 11.0 Booth C 70



11 - 14 November 2014

electronica

Munich, Germany Hall A 5 Booth 101

Colophon

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